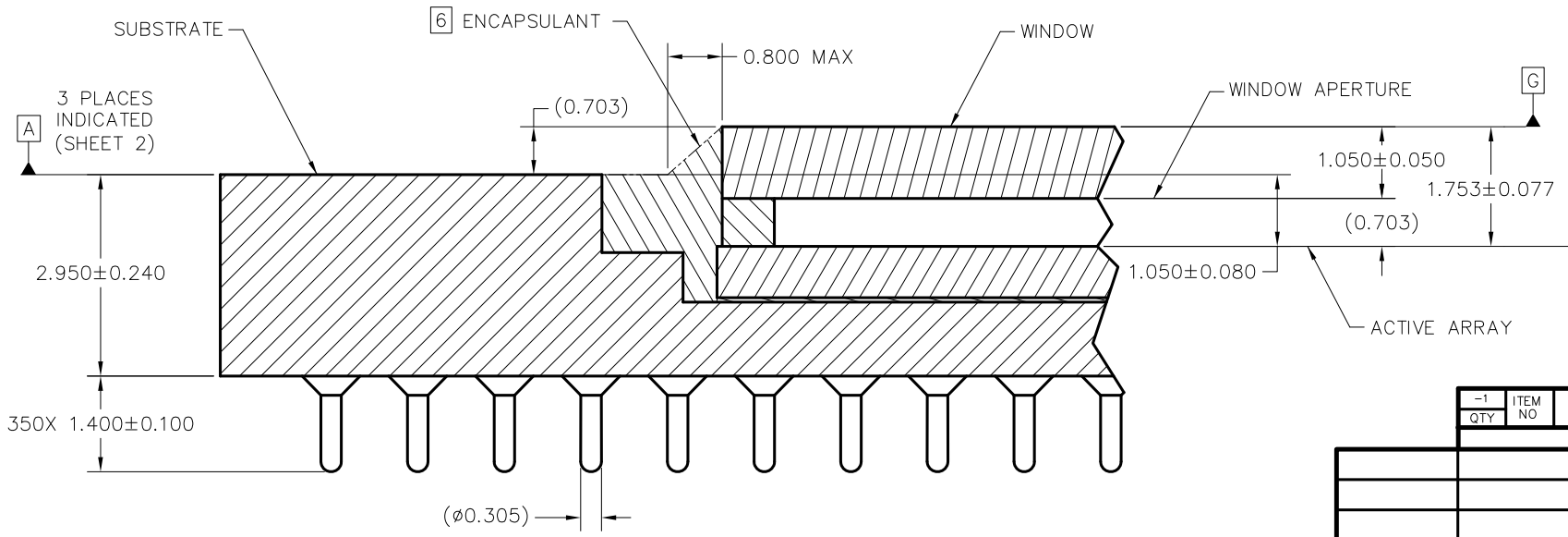
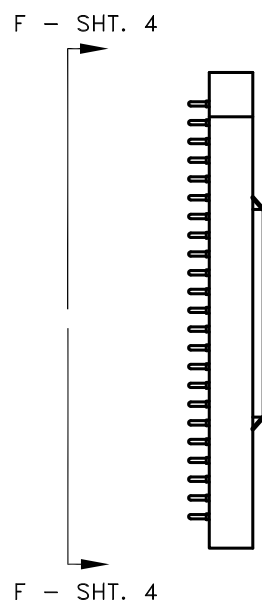
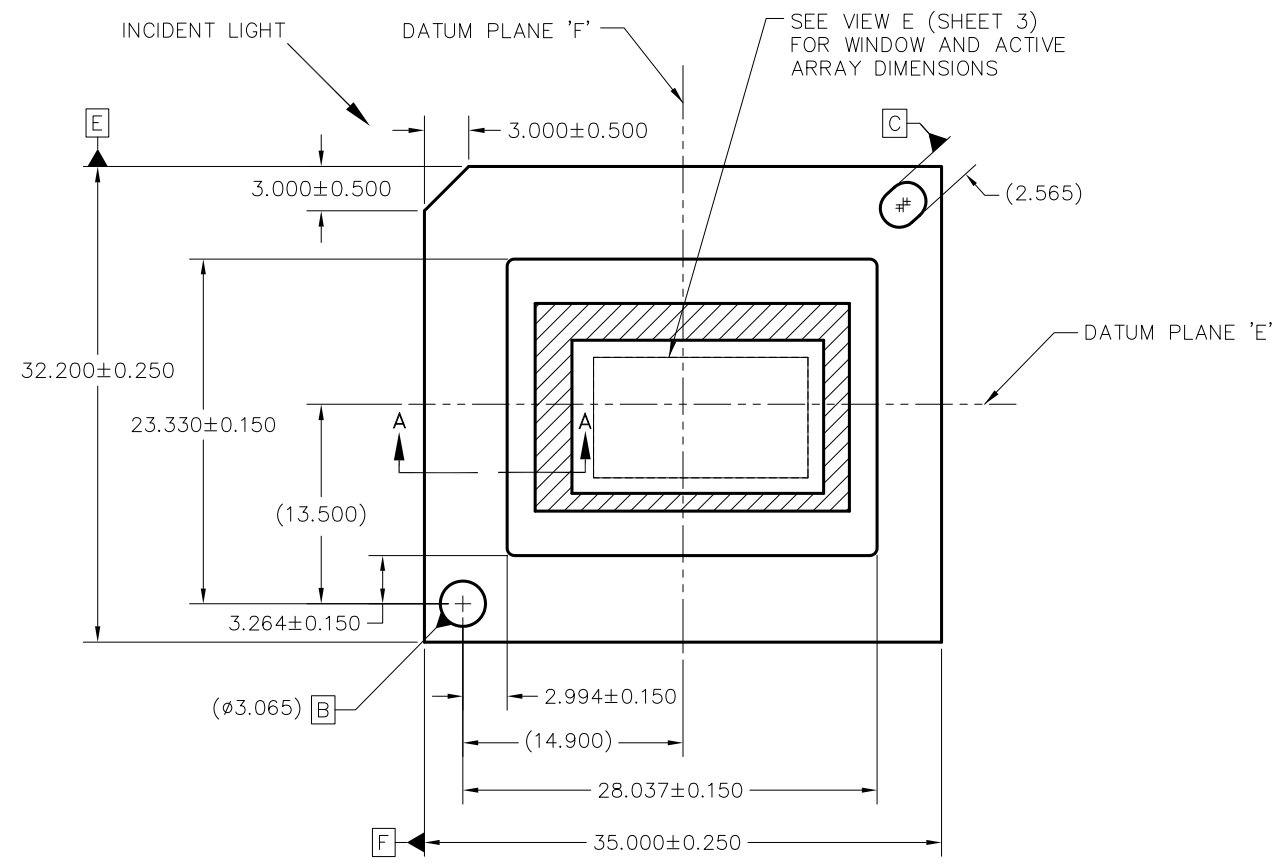
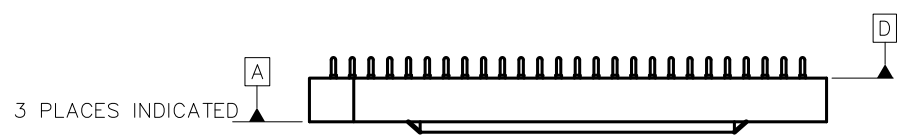


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	ECO 2111739, INITIAL RELEASE	11/04/2010	F. ARMSTRONG
B	ECO 2112602, CHANGE TOLERANCES ON OUTSIDE DIMENSIONS TO ±0.250; CHANGE DATUM B, BACK SIDE PINS, AND DATUM PLANES 'E' AND 'F' TO REFERENCE CENTERLINE OF PART	12/10/2010	F. ARMSTRONG
C	ECO 2135107, ADD NOTE 8 TO SHEETS 1 & 4	08/02/2013	F. ARMSTRONG
D	ECO 2139887, CHG GLASS SIZE UPPER TOL TO +0.050 TO MATCH PROCESS CAPABILITY	02/14/2014	F. ARMSTRONG
E	ECO 2179962, ADD PKG REF DESIGNATOR FYE TO TITLE BLOCK	03/04/2019	F. ARMSTRONG

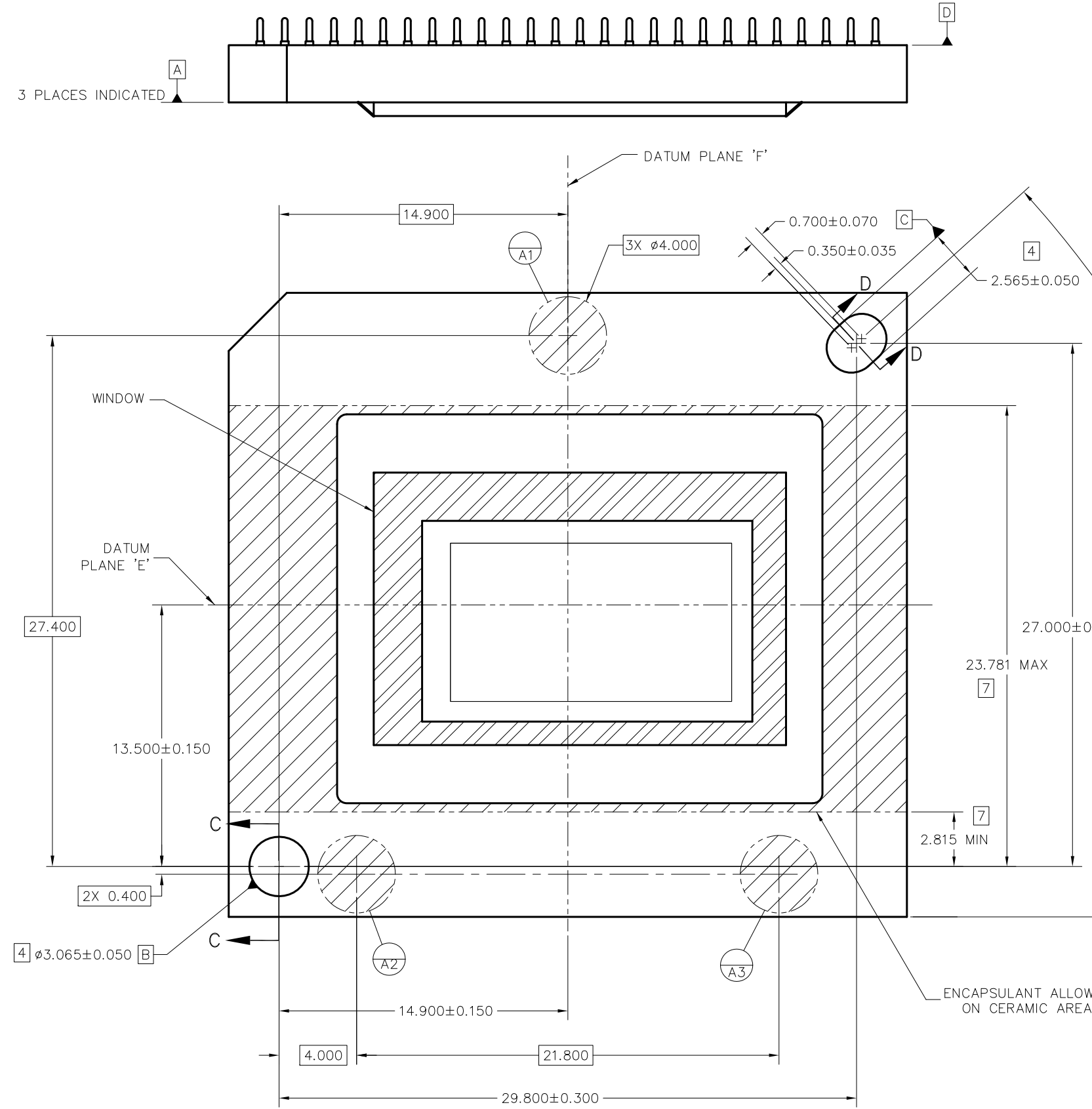
NOTES: UNLESS OTHERWISE SPECIFIED:

- 1 SUBSTRATE EDGE PERPENDICULARITY TOLERANCE APPLIES TO ENTIRE SURFACE
- 2 DIE PARALLELISM TOLERANCE APPLIES TO DMD ACTIVE ARRAY ONLY
- 3 ROTATION ANGLE OF DMD ACTIVE ARRAY IS A REFINEMENT OF THE LOCATION TOLERANCE AND HAS A MAXIMUM ALLOWED VALUE OF 0.8 DEGREES
- 4 SUBSTRATE SYMBOLIZATION PAD, AND PLATING AT BOTTOM OF DATUMS B AND C HOLES ARE ELECTRICALLY CONNECTED TO VSS PLANE WITHIN THE SUBSTRATE
- 5 BOUNDARY MIRRORS SURROUNDING THE DMD ACTIVE AREA
- 6 MAXIMUM ENCAPSULANT PROFILE SHOWN
- 7 ENCAPSULANT ALLOWED ON THE SURFACE OF THE CERAMIC IN THE AREA SHOWN IN VIEW B (SHEET 2). ENCAPSULANT SHALL NOT EXCEED 0.200 THICKNESS MAXIMUM.
- 8 SUBSTRATES PLATED WITH Ni/Au SHALL HAVE THE THREE-DIGIT NUMERICAL MARKING IN THE AREA ABOVE THE SYMBOLIZATION PAD. SUBSTRATES PLATED WITH Ni/Pd/Au SHALL HAVE THE MARKING IN THE AREA BELOW THE SYMBOLIZATION PAD.

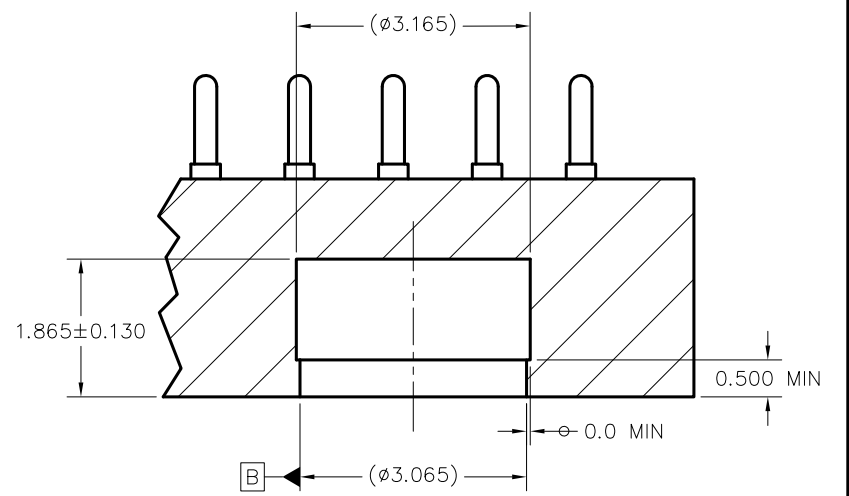


SECTION A-A
SCALE 20/1

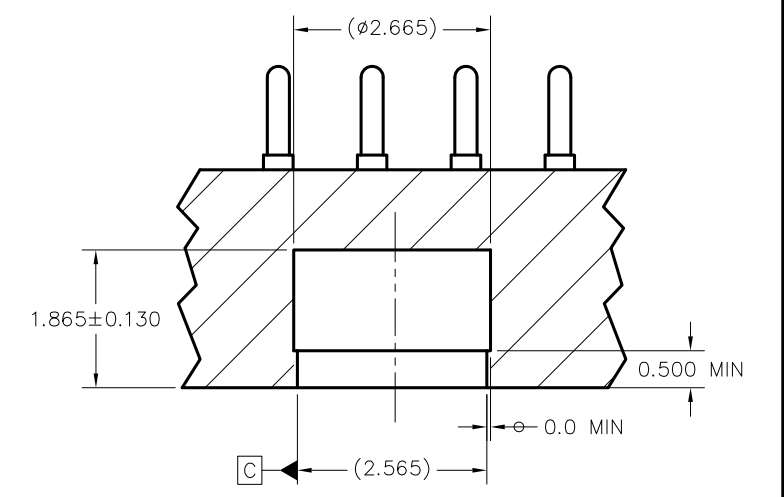
-1 QTY	ITEM NO	PART OR IDENTIFYING NUMBER	NOMENCLATURE OR DESCRIPTION	NOTES
PARTS LIST				
			DWN F. ARMSTRONG 11/02/2010	DATE 11/02/2010
			ENGR F. ARMSTRONG 11/02/2010	
			QA P. KONRAD 11/08/2010	
			COE M. DORAK 11/08/2010	
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES: ANGLES ± 1° 2 PLACE DECIMALS ±0.25 3 PLACE DECIMALS ±0.50				
REMOVE ALL BURRS AND SHARP EDGES INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5-1994 DIMENSIONAL LIMITS APPLY BEFORE PROCESSES PARENTHEICAL INFO FOR REF ONLY			ICD, MECHANICAL, DMD .65 1080p MVSP 2XLVDS SERIES 600 (FYE PACKAGE)	
THIRD ANGLE PROJECTION			SIZE B	REV E
NONE 0314DA			DRAWING NO 2511543	
NEXT ASSY USED ON			SCALE 4/1	SHEET 1 OF 4
APPLICATION				



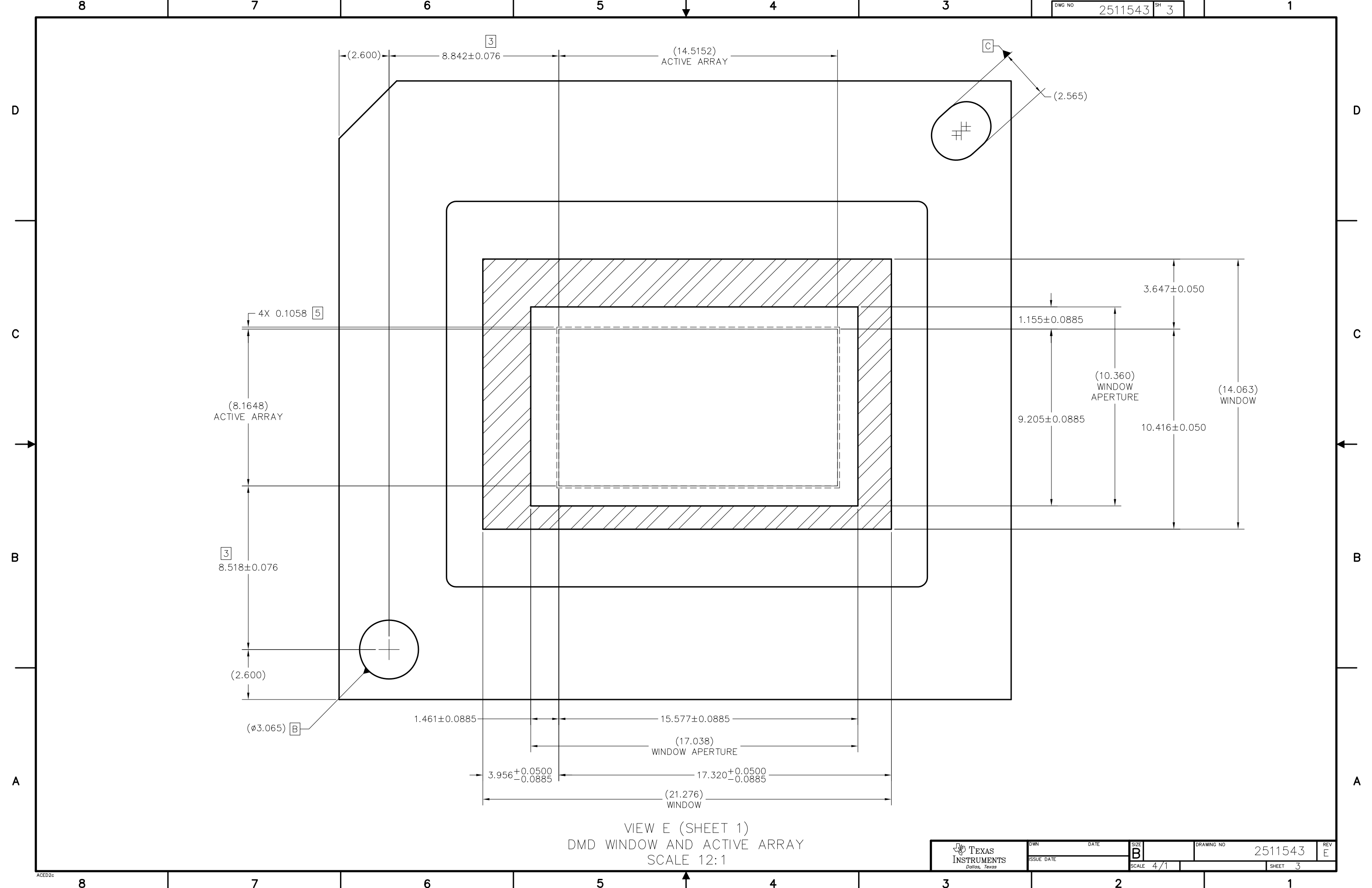
VIEW B
DATUMS AND ENCAPSULANT ALLOWABLE AREA
SCALE 8/1



SECTION C-C
DATUM B
SCALE 16/1



SECTION D-D
DATUM C
SCALE 16/1



(2.600)

8.842±0.076

(14.5152) ACTIVE ARRAY

(2.565)

4X 0.1058

(8.1648) ACTIVE ARRAY

8.518±0.076

(2.600)

(∅3.065)

1.461±0.0885

15.577±0.0885

(17.038) WINDOW APERTURE

3.956^{+0.0500}/_{-0.0885}

17.320^{+0.0500}/_{-0.0885}

(21.276) WINDOW

1.155±0.0885

9.205±0.0885

(10.360) WINDOW APERTURE

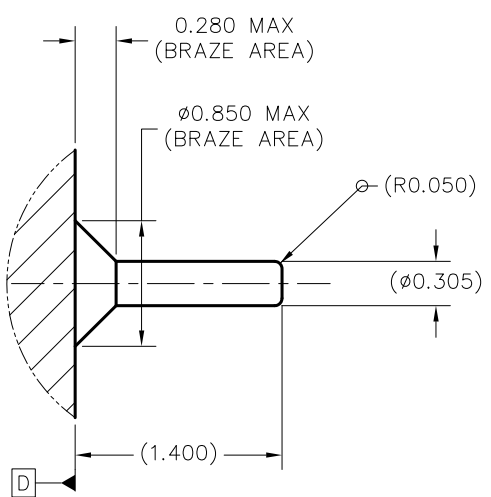
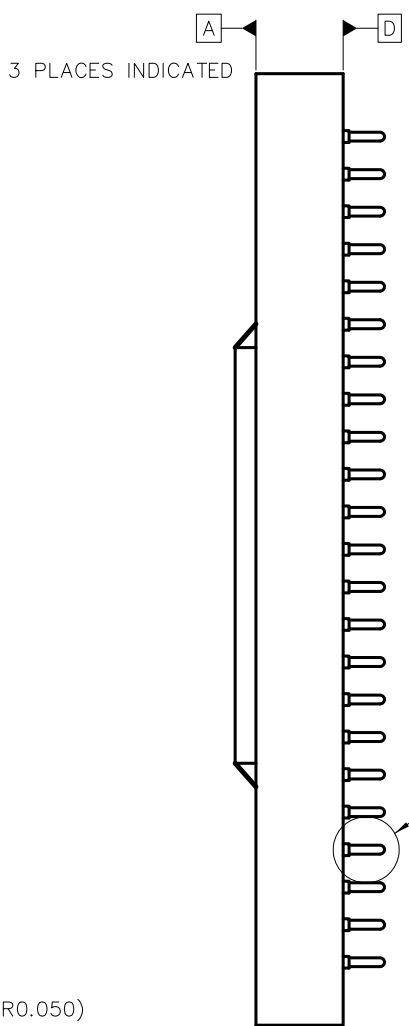
3.647±0.050

10.416±0.050

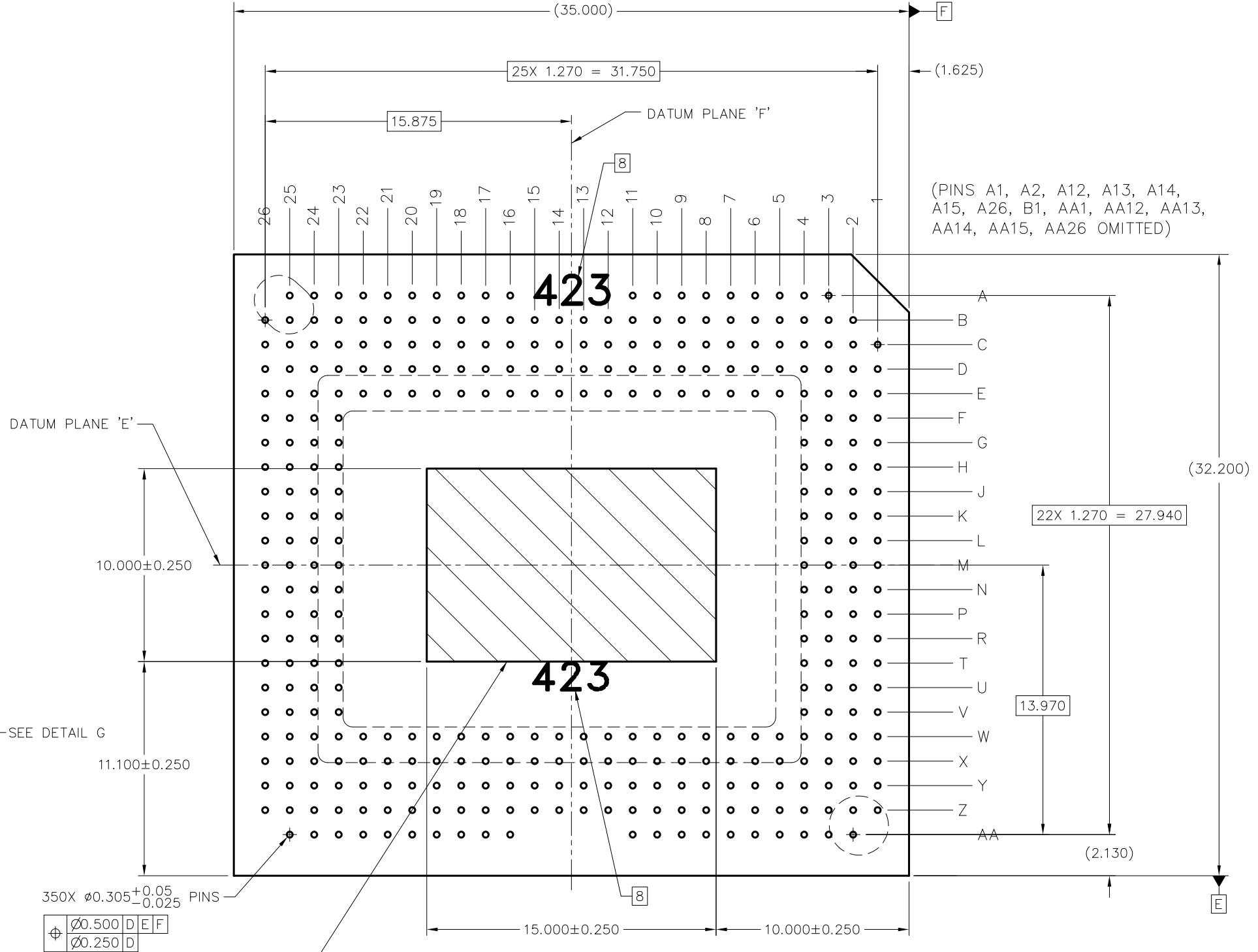
(14.063) WINDOW

VIEW E (SHEET 1)
DMD WINDOW AND ACTIVE ARRAY
SCALE 12:1

TEXAS INSTRUMENTS Dallas, Texas	DWN	DATE	SIZE	DRAWING NO	REV
	ISSUE DATE	SCALE	4/1	2511543	E
				SHEET	3



DETAIL G (350 PLACES)
PIN & BRAZE DIMENSIONS
SCALE 40/1



(PINS A1, A2, A12, A13, A14, A15, A26, B1, AA1, AA12, AA13, AA14, AA15, AA26 OMITTED)

⊕	ø0.500	D	E	F
	ø0.250	D		

4 SYMBOLIZATION PAD

VIEW F-F (SHEET 1)
PINS AND SYMBOLIZATION PAD
SCALE 8/1

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2019, Texas Instruments Incorporated